

#### SSC8030GN2

#### **N-Channel Enhancement Mode MOSFET**

#### > Features

| VDS      | VGS  | RDSON Typ. | ID  |  |
|----------|------|------------|-----|--|
| 201/     | .001 | 8.5mR@10V  |     |  |
| 30V ±20V |      | 10.5mR@4V5 | 17A |  |

## > Description

This device uses advanced trench technology to provide excellent RDSON and low gate charge. This device is suitable for use as a load switch or in PWM applications.

### > Applications

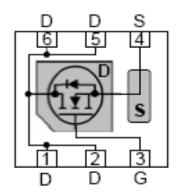
- Load Switch
- PC/NB
- DCDC conversion

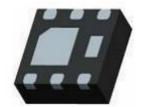
# Ordering Information

| Device     | Package | Shipping  |
|------------|---------|-----------|
| SSC8030GN2 | DFN2x2  | 3000/Reel |

# Pin configuration

Top view





**Bottom View** 

8428.

Marking



### ➤ Absolute Maximum Ratings(T<sub>A</sub>=25°C unless otherwise noted)

| Symbol           | Parameter                             | Ratings    | Unit |
|------------------|---------------------------------------|------------|------|
| $V_{DSS}$        | Drain-to-Source Voltage               | 30         | V    |
| V <sub>GSS</sub> | Gate-to-Source Voltage                | ±20        | V    |
| l <sub>D</sub>   | Continuous Drain Current <sup>a</sup> | 17         | Α    |
| I <sub>DM</sub>  | Pulsed Drain Current <sup>b</sup>     | 52         | Α    |
| P <sub>D</sub>   | Power Dissipation °                   | 4          | W    |
| P <sub>DSM</sub> | Power Dissipation <sup>a</sup>        | 2          | W    |
| TJ               | Operation junction temperature        | -55 to 150 | °C   |
| Тѕтс             | Storage temperature range             | -55 to 150 | °C   |

### ➤ Thermal Resistance Ratings( $T_A=25^{\circ}$ C unless otherwise noted)

| Symbol            | Parameter   | Typical | Maximum | Unit |
|-------------------|---|---------|---------|------|
| R <sub>0</sub> JA | Junction-to-Ambient Thermal Resistance <sup>a</sup> |         | 60      | °C/W |
| Rejc              | Junction-to-Case Thermal Resistance                 |         | 30      | C/VV |

#### Note:

- a. The value of  $R_{\theta JA}$  is measured with the device mounted on 1 in<sup>2</sup> FR-4 board with 2oz.copper,in a still air environment with  $T_A$ =25 $C^{\circ}$ . The value in any given application depends on the user is specific board design. The current rating is based on the t  $\leq$  10s thermal resistance rating.
- b. Repetitive rating, pulse width limited by junction temperature.
- c. The power dissipation  $P_D$  is based on  $T_{J(MAX)}$ =150°C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heat sinking is used.

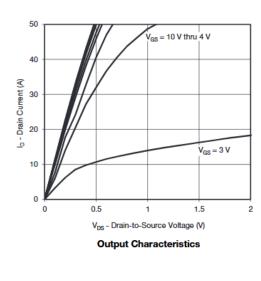


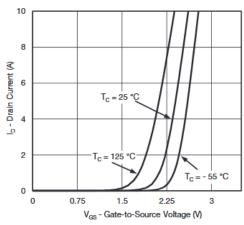
# ➤ **Electronics Characteristics**(T<sub>A</sub>=25°C unless otherwise noted)

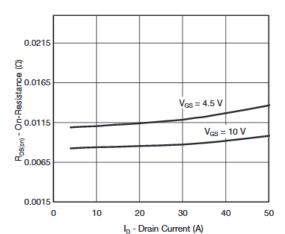
| Symbol               | Parameter                         | Test Conditions         | Min | Тур. | Max  | Unit |
|----------------------|-----------------------------------|-------------------------|-----|------|------|------|
| V <sub>(BR)DSS</sub> | Drain-Source<br>Breakdown Voltage | VGS=0V,ID=250uA         | 30  |      |      | V    |
| V <sub>GS</sub> (th) | Gate Threshold Voltage            | VDS=VGS,ID=250uA        | 1   | 1.5  | 3    | V    |
| Б                    | Drain-Source On-                  | VGS=10V,ID=10A          |     | 8.5  | 10.5 |      |
| R <sub>DS(on)</sub>  | Resistance                        | VGS=4.5V,ID=8A          |     | 10.5 | 14   | mR   |
| I <sub>DSS</sub>     | Zero Gate Voltage  Drain Current  | VDS=24V,VGS=0V          |     |      | 1    | uA   |
| I <sub>GSS</sub>     | Gate-Source leak                  | VGS=±20V,VDS=0V         |     |      | ±100 | nA   |
| G <sub>FS</sub>      | Transconductance                  | VDS=15V,ID=8A           |     | 16   |      | S    |
| V <sub>SD</sub>      | Forward Voltage                   | VGS=0V,IS=1A            |     | 0.8  | 1.5  | V    |
| Ciss                 | Input Capacitance                 |                         |     | 1130 |      |      |
| Coss                 | Output Capacitance                | VDS=15V, VGS=0V, f=1MHz |     | 200  |      | pF   |
| Crss                 | Reverse Transfer Capacitance      |                         |     | 105  |      |      |
| T <sub>D(ON)</sub>   | Turn-on delay time                |                         |     | 18   |      |      |
| Tr                   | Rise Time                         | VGS=10V,                |     | 11   |      |      |
| T <sub>D(OFF)</sub>  | Turn-off delay time               | VDS=15V, RL=2.3R, RG=3R |     | 70   |      | ns   |
| Tf                   | Fall Time                         |                         |     | 16   |      |      |
| Qg                   | Total Gate charge                 |                         |     | 24   |      |      |
| Qgs                  | Gate to Source<br>charge          | VGS=10V, VDS=10V, ID=4A |     | 3    |      | nC   |
| Qgd                  | Gate to Drain charge              |                         |     | 5    |      |      |

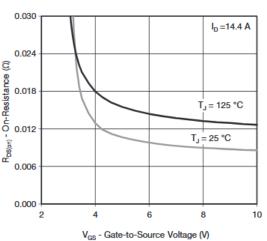


# Typical Characteristics( $T_A$ =25 $^{\circ}$ C unless otherwise noted)





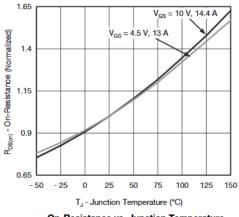


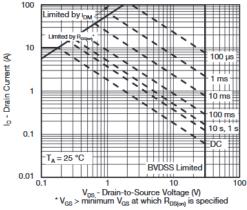


**Transfer Characteristics** 

On-Resistance vs. Drain Current

On-Resistance vs. Gate-to-Source Voltage



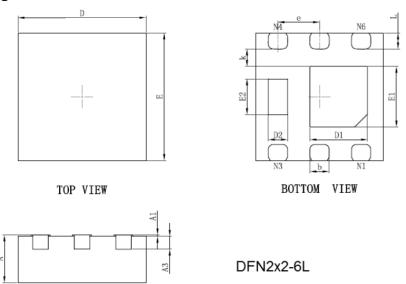


On-Resistance vs. Junction Temperature

Safe Operating Area, Junction-to-Ambient



### Package Information



SIDE VIEW

| Symbol | Dimensions In Millimeters |       |  |
|--------|---------------------------|-------|--|
| Symbol | Min.                      | Max.  |  |
| Α      | 0.700                     | 0.800 |  |
| A1     | 0.000                     | 0.050 |  |
| A3     | 0.203                     | REF.  |  |
| D      | 1.924                     | 2.076 |  |
| E      | 1.924                     | 2.076 |  |
| D1     | 0.800                     | 1.000 |  |
| E1     | 0.850                     | 1.050 |  |
| D2     | 0.200                     | 0.400 |  |
| E2     | 0.460                     | 0.660 |  |
| k      | 0.200MIN.                 |       |  |
| b      | 0.250                     | 0.350 |  |
| е      | 0.650TYP.                 |       |  |
| L      | 0.174                     | 0.326 |  |

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